

TO SEPARATE HO TOP AND BOTTOM EDGES, SNAP APART AND HARD CARBON

RM PTO-892
(REV 2-92)

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

SERIAL NO.

9/530661

GROUP/ART UNIT

2503

ATTACHMENT
TO
PAPER
NUMBER

10

NOTICE OF REFERENCES CITED

APPLICANT(S)

Keeth et al.

U.S. PATENT DOCUMENTS

	DOCUMENT NO	DATE	NAME	CLASS	SUB-CLASS	FILING DATE IF APPROPRIATE
A						
B						
C						
D						
E						
F						
G						
H						
I						
J						
K						

FOREIGN PATENT DOCUMENTS

	DOCUMENT NO	DATE	COUNTRY	NAME	CLASS	SUB-CLASS	PERTINENT SHTS DWG	PP. SPEC
L								
M								
N								
O								
P								
Q								

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

R	Deubner, "Ins at Today's Leading Edge Microprocessors," Semiconductors Internationally 2/94.
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* A copy of this reference is not being furnished with this office action.
(See Manual of Patent Examining Procedure, section 707.05 (a))